

**INFORMATION
DISCLOSURE
STATEMENT**

Atty. Docket No.: 150.00720102

Serial No.: 09/651.217

Applicant(s): Cobbley et al.

Confirmation No.: 2006

Application Filing Date: 30 August 2000

Group: 2829

Information Disclosure Statement mailed: September 5, 2002

U.S. PATENT DOCUMENTS

Examiner Initial	Copy Enclosed	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
SBG		2,628,178	07/29/50	Burnett, et al.			
		3,987,019	10/19/76	Gruber et al.			
		4,209,358	06/24/80	DiLeo et al.			
		4,490,515	12/25/84	Mariotti et al.			
		4,533,422	08/06/85	Litke			
		4,793,887	12/27/88	Card et al.			
		5,150,195	09/22/92	Nguyen			
		5,175,337	12/29/92	Mikuni et al.			
		5,656,945	08/12/97	Cain			
		5,739,205	04/14/98	Nishino et al.			
		5,834,836	11/10/98	Park et al.			
		5,861,678	01/19/99	Schrock			
SBG		6,353,268	03/05/02	Cobbley et al.			

FOREIGN PATENT DOCUMENTS

Examiner Initial	Copy Enclosed	Document Number	Date	Country	Class	Subclass	Translation	
							Yes	No
		None						

OTHER DOCUMENTS (Including Authors, Title, Date, Pertinent Papers, etc.)

Examiner Initial	Copy Enclosed	Document Description
SBG		Denchev et al. "Thermal behaviour and adhesive properties of some cyanoacrylate adhesives with increased heat resistance." <i>J Appl Polym Sci.</i> , 47 1019-1026 (1993).
SBG		Okamoto et al. "Bonding Non-Polar Plastics with Alky Cyanoacrylate Instant Adhesive." Annual Technical Conference and Exhibition, Society of Plastics Engineers (1991).

EXAMINER

Date Considered

*Examiner: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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SBG		Tummala et al., eds., Microelectronics Packaging Handbook, Reinhold, New York, NY 554-557 (1989).

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TECHNICAL STAFF

EXAMINER 	Date Considered 6-7-93
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	Applicant(s): Cobbley et al.	Confirmation No.: 2006
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	Information Disclosure Statement mailed: February 19, 2003	

U.S. PATENT DOCUMENTS

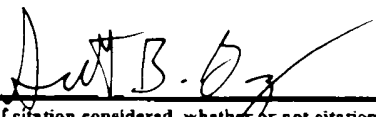
Examiner Initial	Copy Enclosed	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
S.B.G.	X	4,837,260	06/06/89	Sato et al.	—	—	

FOREIGN PATENT DOCUMENTS

Examiner Initial	Copy Enclosed	Document Number	Date	Country	Class	Subclass	Translation	
							Yes	No

OTHER DOCUMENTS (Including Authors, Title, Date, Pertinent Papers, etc.)

Examiner Initial	Copy Enclosed	Document Description

EXAMINER 	Date Considered 6-9-03
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